Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material–UL Flammability 94V-O

Mechanical Date

- Case:ABS, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number

Package: ABS

Major Ratings and Characteristics

I_O	0.8A, 1A
V_{RRM}	200V ~ 1000V
I_{FSM}	30 A
I_R	5 μA
V_F	1.00 V
T_j (max.)	150℃

■ Maximum Ratings & Thermal Characteristics (T_A=25℃, unless otherwise noted)

Items	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	UNIT
Peak Repetitive Reverse Voltage DC Blocking Voltage	V_{RRM} V_{DC}	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	140	280	420	560	700	
Average Rectified Output Current (1) Average Rectified Output Current (2)	I_O	0.8 1.0					A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load(JEDEC Method)	I_{FSM}	30					
Current Squared Time	I^2t	3.7					A^2S
Thermal resistance from junction to lead (1)	$R_{\theta JL}$	25					℃/W
Thermal resistance from junction to ambient (1)	$R_{\theta JA}$	80					
Thermal resistance from junction to ambient (2)	$R_{\theta JA}$	62.5					
Operating junction temperature range	T_J	-55 to +150					℃
Storage temperature range	T_{STG}	-55 to +125					

Note 1 : Mounted on glass epoxy PC board with 1.3mm² solder pad.
Note 2 : Mounted on aluminum substrate PC board with 1.3mm² solder pad.

■ Electrical Characteristics (T_A=25℃, unless otherwise noted)

Items	Test conditions		Symbol	Min	Typ	Max	UNIT
Instantaneous forward voltage per leg	I_F=1.0A (3)		V_F	--	--	1	V
Reverse current	V_R=V_{DC}	T_j=25℃	I_R	--	--	5	μA
		T_j=100℃		--	--	500	

Note 3 : Pulse test: 300μs pulse width, 1% duty cycle.

Characteristic Curves (T_A=25℃ unless otherwise noted)

Fig.1: Output Current Derating Curve

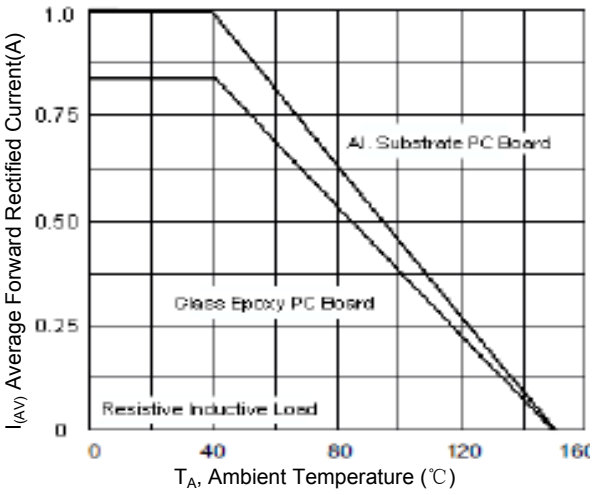


Fig.2: Typical Forward Characteristics (per leg)

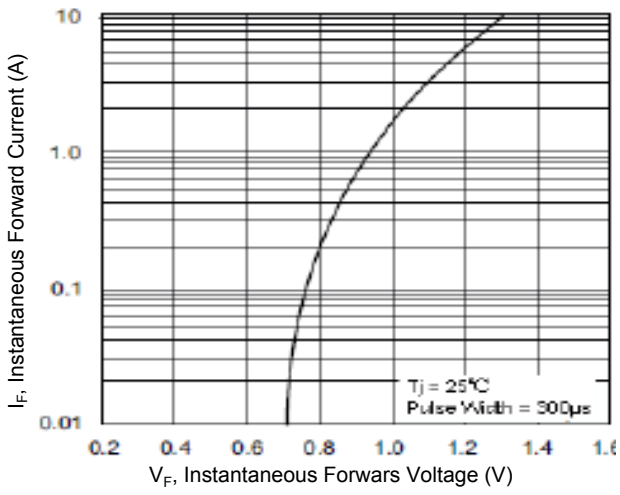


Fig.3: Max. Peak Forward Surge Current (per leg)

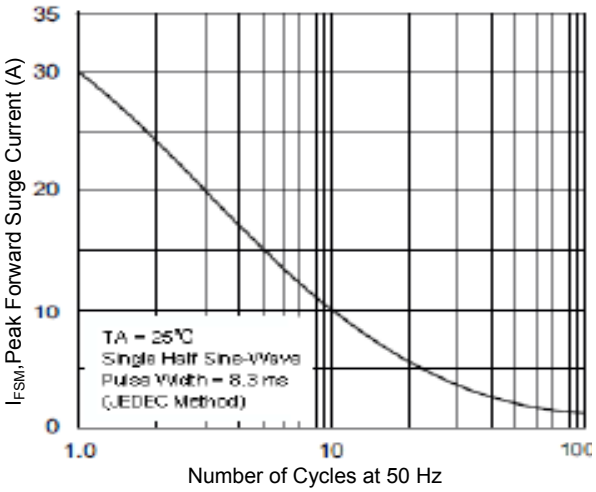


Fig.4: Typical Junction Capacitance

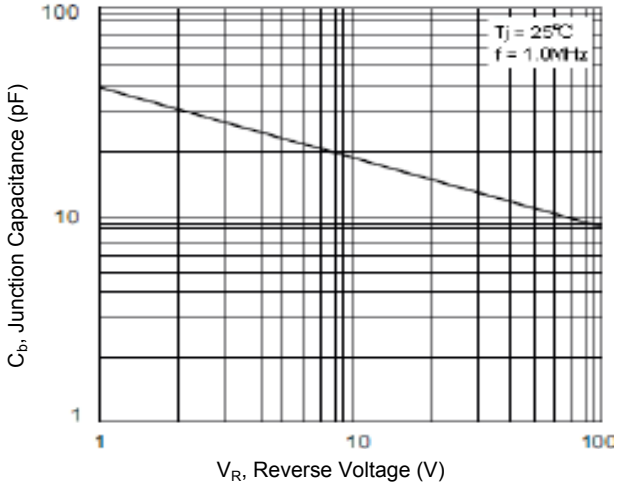
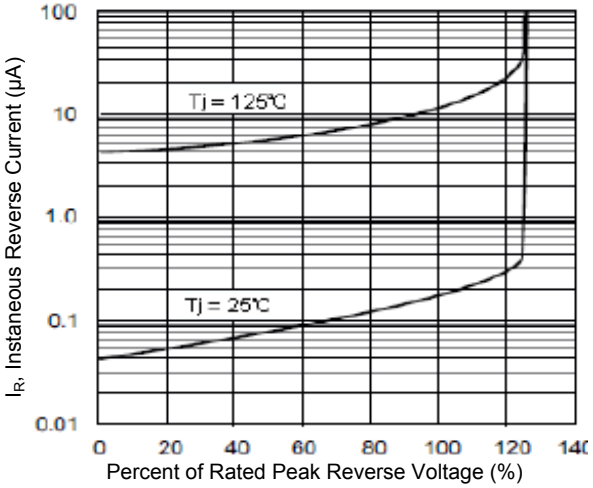
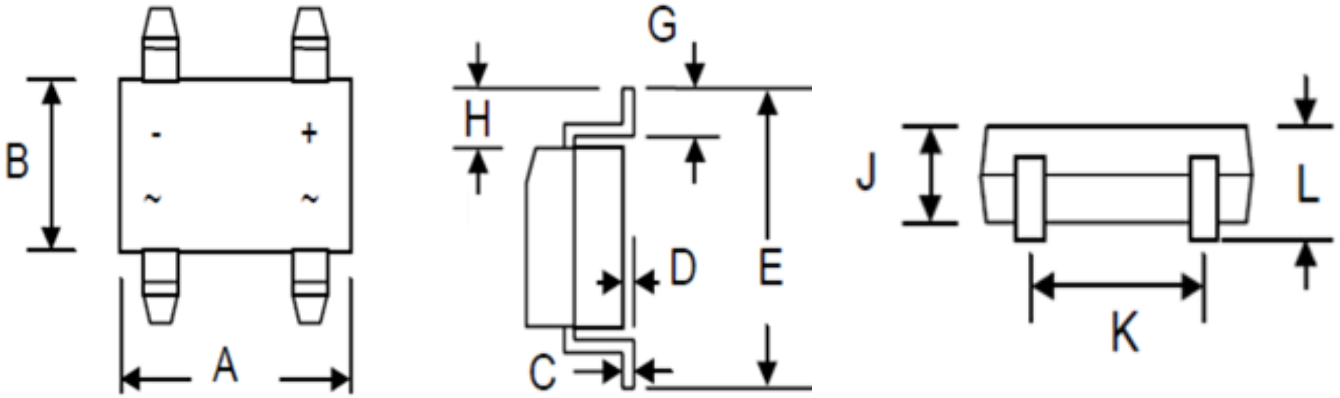


Fig.5: Typical Reverse Characteristics (per element)



Package Outline

ABS



UNIT: mm (inch)

DIM	MIN	MAX	DIM	MIN	MAX
A	4.90 (0.154)	5.30 (0.209)	G	0.30 (0.012)	0.80 (0.032)
B	4.30 (0.169)	4.80 (0.189)	H	0.80 (0.032)	1.20 (0.047)
C	0.15 (0.006)	0.25 (0.010)	J	1.20 (0.047)	1.40 (0.055)
D	0.05 (0.002)	0.15 (0.006)	K	3.80 (0.150)	4.20 (0.165)
E	6.00 (0.236)	6.40 (0.252)	L	--	1.50 (0.059)

April 20, 2014
2014-02-20_TRR_1.0

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